Notice of Allowability	Application No.	Applicant(s)	
	10/051,906 Examiner	SU ET AL. Art Unit	
	John Ruggles	1756	
The MAILING DATE of this communication ap All claims being allowable, PROSECUTION ON THE MERITS I herewith (or previously mailed), a Notice of Allowance (PTOL-8 NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT of the Office or upon petition by the applicant. See 37 CFR 1.3	S (OR REMAINS) CLOSED in 5) or other appropriate common RIGHTS. This application is s	n this application. If not includ unication will be mailed in due	ed course. THIS
1. \boxtimes This communication is responsive to <u>the submissions file</u>	<u>ed on 5/13/05</u> .		
2. ☑ The allowed claim(s) is/are <u>1-4,8,10-19 and 21-24</u> .			
3. \boxtimes The drawings filed on <u>13 May 2005</u> are accepted by the	Examiner.		
4. Acknowledgment is made of a claim for foreign priority a) All b) Some* c) None of the: 1. Certified copies of the priority documents ha 2. Certified copies of the priority documents ha 3. Copies of the certified copies of the priority of International Bureau (PCT Rule 17.2(a)). * Certified copies not received: Applicant has THREE MONTHS FROM THE "MAILING DATE noted below. Failure to timely comply will result in ABANDON THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. 5. A SUBSTITUTE OATH OR DECLARATION must be sub INFORMAL PATENT APPLICATION (PTO-152) which give the Corrected DRAWINGS (as "replacement sheets") metalling changes required by the Notice of Draftsperior.	ve been received. ve been received in Application documents have been received. E" of this communication to file IMENT of this application. mitted. Note the attached EXAIVES reason(s) why the oath or ust be submitted. erson's Patent Drawing Review	on No d in this national stage applicate a reply complying with the re AMINER'S AMENDMENT or Not declaration is deficient.	quirements
1) ☐ hereto or 2) ☐ to Paper No./Mail Date (b) ☐ including changes required by the attached Examine Paper No./Mail Date		in the Office action of	
Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in			a back) of
 DEPOSIT OF and/or INFORMATION about the department department regarding REQUIREMEN 			Note the
 Attachment(s) 1. ☐ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SE Paper No./Mail Date) 6. ☐ Interview Si Paper No./ 3/08), 7. ☐ Examiner's	formal Patent Application (PToummary (PTO-413), Mail Date Amendment/Comment Statement of Reasons for Allo John Ruggles Examiner, Art Unit	owance

Response to Amendment

The supplemental amendment #2 filed on 5/13/05 to correct Figure 3A has been entered.

Allowable Subject Matter

Claims 1-4, 8, 10-19, and 21-24 are allowed.

The following is an examiner's statement of reasons for allowance: Applicants' arguments filed on 5/13/05 have been fully considered and are now persuasive. The prior art does not clearly teach the claim 1 limitation of forming a temporary protective layer over a passivation layer and an exposed UBM layer, in which the protective layer comprises a resinous organic material (recited to comprise benzocyclobutene (BCB) in dependent claim 3) having a glass transition temperature (T_g) that is about greater than (defined at page 18 lines 3-4 to mean equal to or greater than) a solder reflow temperature for protecting a semiconductor process wafer surface from thermally degraded photoresist to improve a solder ball formation process. Therefore, claim 1 is allowable over the prior art and claims 2-4, 8, 10, and 21-22 are also allowable, due to their dependence on claim 1. Similarly, the prior art does not clearly teach the claim 11 limitation of forming a temporary protective layer overlying a semiconductor wafer process surface that comprises a UBM contact layer, in which the protective layer comprises a resinous organic material (recited to comprise benzocyclobutene (BCB) in dependent claim 13) having a glass transition temperature (T_g) that is greater than a solder column reflow temperature for forming a solder ball to avoid photoresist residue in a solder ball formation process. Therefore, claim 11 is allowable over the prior art and claims 12-19 and 23-24 are also allowable, due to their dependence on claim 11.

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Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to John Ruggles whose telephone number is 571-272-1390. The examiner can normally be reached on Monday-Thursday and alternate Fridays.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Mark Huff can be reached on 571-272-1385. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

hn Ruggles

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